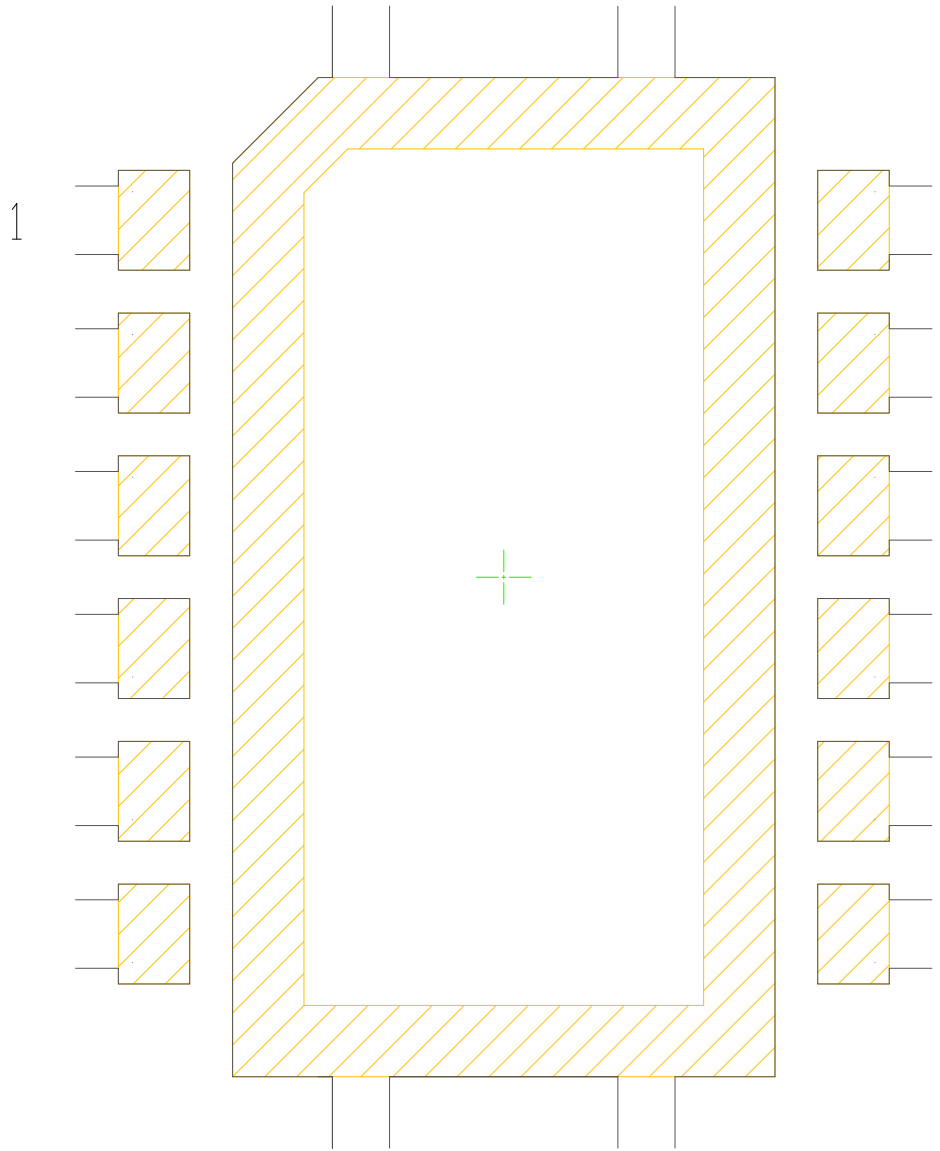



REVISIONS		
REV	DESCRIPTION	DATE
C	CHANGE TO SELECTIVE PLATING (GROUND RING)	5-17-18



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 3.50 x 1.90 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 3.30 x 1.70 mm	TITLE DFN 12L 4x3 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: FULL PLATING	LEADFRAME P/N: 235-00076
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	REV 00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE
		FILE NAME 12L-DFN-4X3-50P-BD.DWG
		SHEET 1 OF 1